IGBT Modules

Power Module (V series) 1200V / 100A / 2-in-1 package

■ Features

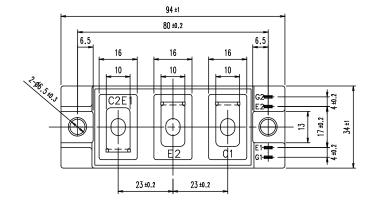
AC-switch
High speed switching
Voltage drive
Low Inductance module structure

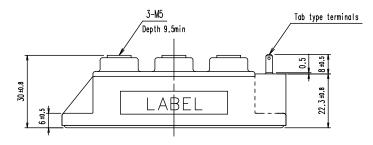
■ Applications

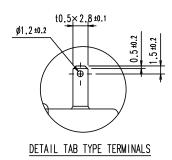
AC-switch for UPS,PCS and etc.

■ Outline drawing (Unit:mm)



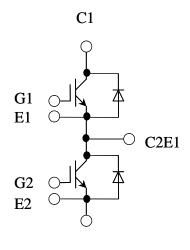






Weight: 180g (typ.)

■ Equivalent circuit



E2



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■ Absolute maximum ratings (at T_C= 25°C unless otherwise specified)

Items		Symbols	Conditions	Maximum ratings	Units
Collector-En	nitter voltage	V _{CES}		1200	V
Gate-Emitte	r voltage	V _{GES}		±20	V
Collector current		I _C	Continuous T _C =100°C	100	
		I _C pulse	1ms	200	Α
Collector cu	ilelit	-1 _C		100	A
		-/ _C pulse	1ms	200	
Collector power dissipation		Pc	1 device	555	W
Junction temperature		T _i		175	
Operating junction temperature		T_{jop}		150	0.0
(under switching conditions)					°C
Case temperature		Tc		125	
Storage temperature		${T}_{ m stg}$		-40 ~ 125	
Isolation	Between terminal and copper base	V _{iso}	AC: 1min.	2500	VAC
voltage	(*1)	v iso	AC. IIIIII.	2500	VAC
Screw	Mounting	-	M5 or M6	3.0~5.0	N m
torque	Terminals	-	M5	2.5~5.0	IN III

^(*1) All terminals should be connected together when isolation test will be done.

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■ Electrical characteristics (at T_i= 25°C unless otherwise specified)

NOTICE:

The external gate resistance (R_g) shown below is one of our recommend value for the purpose of minimum switching loss. However the optimum R_g depends on circuit configuration and/or environment. We recommend that the R_g has to be carefully chosen based on consideration if IGBT module matches design criteria, for example, switching loss, EMC/EMI, spike voltage, surge current and no unexpected oscillation and so on.

Itomo	Cumbala	Condition	no	Ch	aracterist	ics	Units
Items	Symbols	Condition	ons	min.	typ.	max.	Units
Zero gate voltage collector current	I _{CES}	V _{GE} =0V,V _{CE} =1200V		-	-	1.0	mA
Gate-Emitter leakage current	I _{GES}	$V_{CE} = 0V, V_{GE} = \pm 20V$		-	-	200	nA
Gate-Emitter threshold voltage	$V_{GE(th)}$	V _{CE} =20V,I _C =100mA	1	6.0	6.5	7.0	V
	V		T _j =25°C	-	1.90	2.35	
	V _{CE(sat)}	V_{GE} =15V, I_{C} =100A	T _j =125°C	-	2.20	-	
Collector-Emitter	(terminal)		T _j =150°C	-	2.25	-	V
saturation voltage	V		T _j =25°C	-	1.75	2.20	7 V
	V _{CE(sat)}	V_{GE} =15V, I_{C} =100A	T _j =125°C	-	2.05	-	
	(chip)		T _j =150°C	-	2.10	-	0
Internal gate resistance	$R_{g(int)}$	-	•	-	7.5	-	Ω
Input capacitance	C _{ies}	V_{CE} =10V, V_{GE} =0V, j	V_{CE} =10V, V_{GE} =0V, f =1MHz		9.1	-	nF
	t on			-	600	-	
Turn-on time	t _r	$V_{\rm CC}$ =600V, $I_{\rm C}$ =100A, $V_{\rm GE}$ =±15V,		-	200	-	nsec
	t _{r(i)}		-	50	-		
Turn-off time	t off	$R_{\rm g}$ =1.6 Ω , $T_{\rm j}$ =150°C, $L_{\rm s}$ =30nH		-	600	-	
Turn-on time	t _f			-	40	-	
	V _F		T _i =25°C	-	1.80	2.25	
		$V_{GE} = 0V, I_{F} = 100A$	T _j =125°C	-	1.95	-	
Converd on velters	(terminal)		T _i =150°C	-	1.90	-	V
Forward on voltage	V _F		T _i =25°C	-	1.70	2.15	_ v
		$V_{GE} = 0V, I_{F} = 100A$	T _i =125°C	-	1.85	-	
	(chip)		T _j =150°C	-	1.80	-	7
Reverse recovery time	t _{rr}	I _F =100A		-	150	-	nsec

■ Thermal resistance characteristics

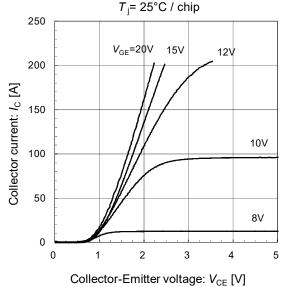
Items	Symbols	Conditions	Characteristics			Units
	Symbols	Conditions	min.	typ.	max.	UIIIIS
Thermal resistance	P	IGBT	-	-	0.27	
(1device)	R _{th(j-c)}	FWD	-	-	0.48	°C/W
Contact thermal resistance (1device) (*1)	R _{th(c-f)}	with thermal compound	-	0.050	-	C/VV

^(*1) This is the value which is defined mounting on the additional cooling fin with thermal compound.

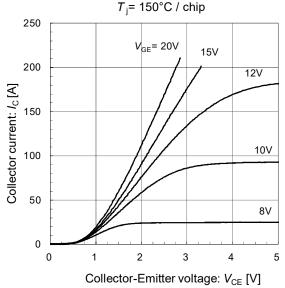


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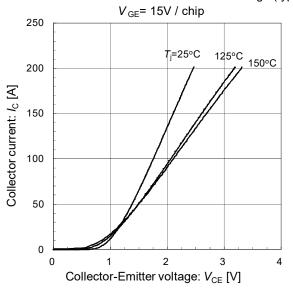
Collector current vs. Collector-Emitter voltage (typ.)



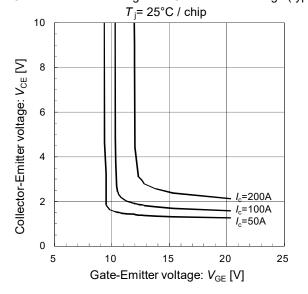
Collector current vs. Collector-Emitter voltage (typ.)



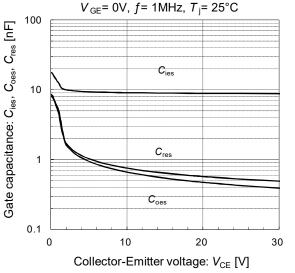
Collector current vs. Collector-Emitter voltage (typ.)

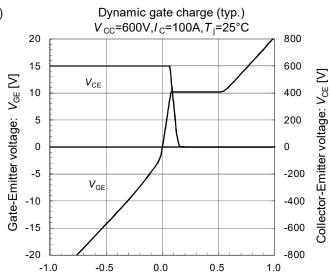


Collector-Emitter voltage vs. Gate-Emitter voltage (typ.)



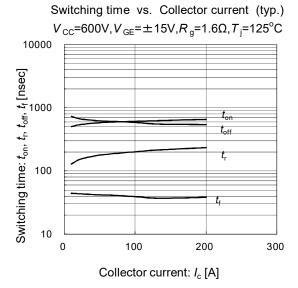


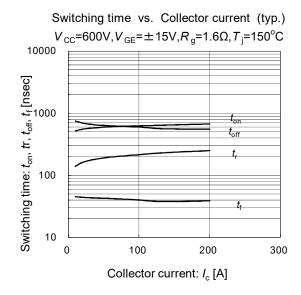


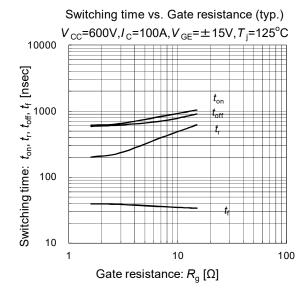


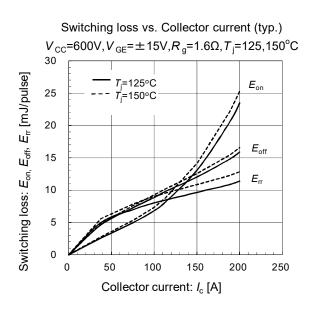
Gate charge: Q_q [µC]

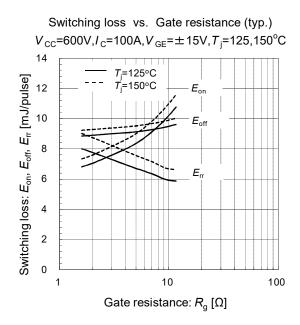
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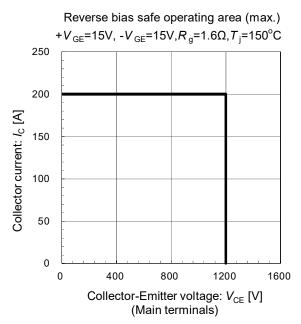






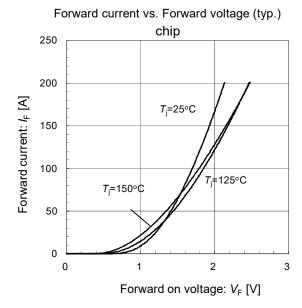


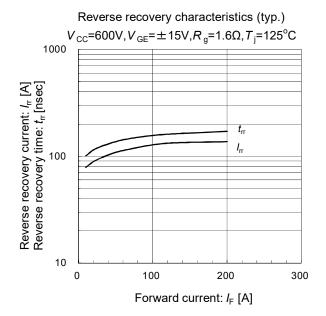


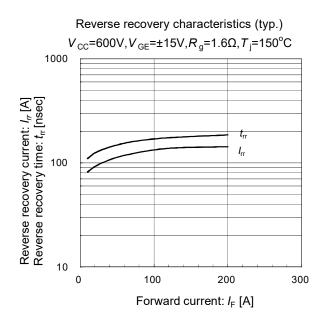




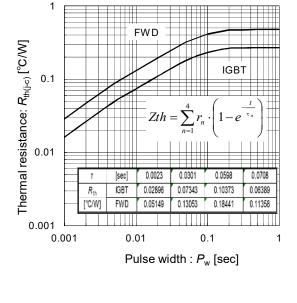
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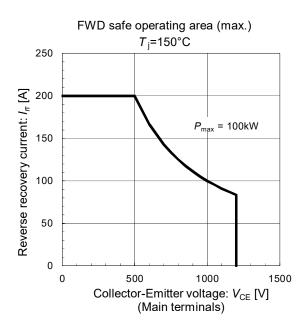














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